

LOW PROFILE INTEGRATED MODULE INTERCONNECTS
5 AND METHOD OF FABRICATION

Abstract of the Disclosure

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A low profile integrated module is fabricated to include sheets of material, such as ceramic or PCB, fixed together and including a via extending through at least one of the plurality of sheets from the lower module 15 surface partially to the upper module surface and in a side module surface. The via is filled with conductive material. The module is then mounted on a supporting substrate having a solder pad on the mounting surface with an area greater than the lower surface of the via. The 20 lower surface of the via is positioned adjacent the upper surface of the mounting pad and soldered so that solder wicks up the via along the side module surface.